



News Release

nVent Launches the COM Nano System

LONDON – February 25, 2020 – nVent Electric plc (NYSE:NVT) (“nVent”), a global leader in electrical connection and protection solutions, today announced it has added the nVent SCHROFF COM Nano System to the company’s product offering. The COM Nano System is a powerful computer which measures 140 mm x 115 mm x 45 mm and works with all common PC interfaces. It is based on the nVent SCHROFF COM Carrier System and consists of a modular COM Carrier and a COM Express Type 6 module.

To fit different IP levels, the mechanical case is designed to adapt to several application requirements. The COM Nano System consists of a milled inner case, which also acts as the thermal interface for the processor and other thermal hot spots. An integrated EMC/IP gasket ensures ingress protection class IP53 providing protection against dust and foreign particles, contact and falling water spray at up to 60 degrees from the vertical. A separate U-profile covers the inner case, providing thermal ingress protection. The available PC interfaces – 2x Gigabit Ethernet, 3x USB and a DisplayPort– are recessed into the underside of the case. On the front of the case, there is a small control panel with a push button and a display to indicate the operating status and hard disk activity.

To enable fast processor performance adaptation, the COM Nano System is equipped with Congatec TC370 series modules, which have eighth generation Intel processors (series i3, i5, i7). These modules work as mobile processors with four cores from Core i5 upwards and result in superior performance, especially for multi-core applications. Other features include up to 64 GB RAM memory, an m.2 NVMe SSD connected via PCIe and an external 12V power supply unit.

To meet the cooling requirements for a variety of applications, the COM Nano System is available in three configurations. In the first configuration, an integrated heat sink dissipates the heat passively. In the second configuration, a radial fan located within the case, supports

the thermal transfer through the heat sink by circulating the air. The third configuration provides the best thermal performance because a radial fan cools the electronic components that do not have a conduction cooled thermal pathway. It also features a heat sink. For configurations with fans, the design ensures IP protection because the downward pointing, negative-V-shape of the cooling fins prevents water from entering the fan and the case interior.

Further customization is possible. Learn more at

<https://schroff.nvent.com/wcsstore/ExtendedSitesCatalogAssetStore/Attachment/SchroffAttachments/DownloadCenter/SCHROFF-SLSH-H85720-COMNano-EN.pdf>



About nVent

nVent is a leading global provider of electrical connection and protection solutions. We believe our inventive electrical solutions enable safer systems and ensure a more secure world. We design, manufacture, market, install and service high performance products and solutions that connect and protect some of the world's most sensitive equipment, buildings and critical processes. We offer a comprehensive range of enclosures, electrical connections and fastening and thermal management solutions across industry-leading brands that are recognized globally for quality, reliability and innovation. Our principal office is in London, United Kingdom and our management office in the United States is in Minneapolis, Minnesota. Our robust portfolio of leading electrical product brands dates back more than 100 years and includes nVent CADDY, ERICO, HOFFMAN, RAYCHEM, SCHROFF and TRACER.

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